

ABSTRACT

The present disclosure provides a polishing head and a wafer polishing device having the same. The polishing head includes: a main body; and an elastic membrane assembly on the main body, wherein the elastic membrane assembly comprises an inner membrane and an outer membrane that are nested; the inner membrane is fixed to a bottom wall of the main body; the inner membrane is formed with a plurality of mutually independent pressure chambers for acting on a central area of a wafer; the outer membrane is fitted around outer peripheral side of the main body; the outer membrane covers the inner membrane, and a buffer gap is provided between the outer membrane and the inner membrane; wherein during a grinding process, the inner membrane exerts force on the wafer through the outer membrane. The present disclosure provides the elastic membrane assembly which includes the inner membrane and the outer membrane that are nested. During the grinding process, since the reaction force on the polishing head by the wafer is directly exerted on the outer membrane rather than the inner membrane, the radial deformation or displacement of the outer membrane relative to the main body would not directly cause deformation or displacement of the inner membrane. Therefore, it can reduce the degree of displacement or deformation of the inner membrane, thereby improving the flatness of the grinding surface and effectiveness of the process.

[Fig. 1]